

	Type	Hits	Search Text	DBs
54	BRS	2340	flexible near3 die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
55	BRS	376	flexible near3 die and integrated adj (circuit circuits)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
56	BRS	253	flexible near3 die and integrated adj (circuit circuits) and bonding	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
57	BRS	211	flexible near3 die and integrated adj (circuit circuits) and bonding and(bonding bond bonded) with die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
58	BRS	148	flexible near3 die and integrated adj (circuit circuits) and bonding and(bonding bond bonded) with die and plurality with die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
59	BRS	55	flexible near3 die and integrated adj (circuit circuits) and bonding and(bonding bond bonded) with die and plurality with die and (stack stacking stacked)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
60	BRS	1533	flexible near2 die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
61	BRS	644	flexible adj2 die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
62	BRS	262	flexible near2 die and integrated adj (circuit circuits)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Time Stamp	Comments	Error Definition	Errors	Ref #
54	2005/08/09 12:00				S55
55	2005/08/09 11:54				S56
56	2005/08/09 11:54				S57
57	2005/08/09 11:54				S58
58	2005/08/09 11:54				S59
59	2005/08/09 11:55				S60
60	2005/08/09 11:53				S61
61	2005/08/09 11:53				S62
62	2005/08/09 11:54				S63

	Type	Hits	Search Text	DBs
63	BRS	50	flexible adj2 die and integrated adj (circuit circuits)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
64	BRS	189	flexible near2 die and integrated adj (circuit circuits) and bonding	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
65	BRS	40	flexible adj2 die and integrated adj (circuit circuits) and bonding	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
66	BRS	162	flexible near2 die and integrated adj (circuit circuits) and bonding and(bonding bond bonded) with die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
67	BRS	32	flexible adj2 die and integrated adj (circuit circuits) and bonding and(bonding bond bonded) with die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
68	BRS	118	flexible near2 die and integrated adj (circuit circuits) and bonding and(bonding bond bonded) with die and plurality with die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
69	BRS	21	flexible adj2 die and integrated adj (circuit circuits) and bonding and(bonding bond bonded) with die and plurality with die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
70	BRS	8	flexible adj2 die and integrated adj (circuit circuits) and bonding and(bonding bond bonded) with die and plurality with die and (stack stacking stacked)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
71	BRS	43	flexible near2 die and integrated adj (circuit circuits) and bonding and(bonding bond bonded) with die and plurality with die and (stack stacking stacked)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Time Stamp	Comments	Error Definition	Errors	Ref #
63	2005/08/09 11:54				S64
64	2005/08/09 11:54				S65
65	2005/08/09 11:54				S66
66	2005/08/09 11:54				S67
67	2005/08/09 11:54				S68
68	2005/08/09 11:55				S69
69	2005/08/09 11:55				S70
70	2005/08/09 11:55				S72
71	2005/08/09 11:59				S71

	Type	Hits	Search Text	DBs
72	BRS	2	"20040097008"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
73	BRS	40535	flexible near3 (circuit circuits)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
74	BRS	35565	flexible near2 (circuit circuits)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
75	BRS	30865	flexible adj2 (circuit circuits)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
76	BRS	2	"6632706".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
77	BRS	0	("4724328" "4835765" "4919749" "7994336" "5144142" "5262341" "5358909" "5514628" "5620915" "5637907" "6445006" "6682981" "6713327" "6714625" "6765279" "6838896").pn. and flexible near3 die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
78	BRS	3	"20030223535" "20030218182" and flexible near3 die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
79	BRS	2	("20030223535" "20030218182") and flexible near3 die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Time Stamp	Comments	Error Definition	Errors	Ref #
72	2005/08/09 11:59				S73
73	2005/08/09 12:00				S74
74	2005/08/09 12:00				S75
75	2005/08/09 12:00				S76
76	2005/08/09 14:17				S77
77	2005/08/09 14:19				S80
78	2005/08/09 14:19				S82
79	2005/08/09 14:20				S83

	Type	Hits	Search Text	DBs
80	BRS	25	("4724328" "4835765" "4919749" "7994336" "5144142" "5262341" "5358909" "5514628" "5620915" "5637907" "6445006" "6682981" "6713327" "6714625" "6765279" "6838896") .pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
81	BRS	3	"20030223535" "20030218182"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
82	BRS	1	gb-2125168-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
83	BRS	2	jp-63076484-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
84	BRS	1	jp-02037655-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
85	BRS	2	jp-03127816-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
86	BRS	2	jp-03174715-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
87	BRS	2	ep-518283-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Time Stamp	Comments	Error Definition	Errors	Ref #
80	2005/08/09 14:23				S78
81	2005/08/09 14:24				S81
82	2005/08/09 14:24				S84
83	2005/08/09 14:24				S85
84	2005/08/09 14:25				S87
85	2005/08/09 14:25				S88
86	2005/08/09 14:26				S89
87	2005/08/09 14:26				S90

	Type	Hits	Search Text	DBs
88	BRS	1	wo-2003078305-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
89	BRS	324	(flexible and integrated adj (circuit circuits) and substrate).clm.	US-PGPUB
90	BRS	110	(flexible and integrated adj (circuit circuits) and substrate and (bond bonding bonded)).clm.	US-PGPUB
91	BRS	81	(flexible with substrate and integrated adj (circuit circuits) and substrate and (bond bonding bonded)).clm.	US-PGPUB
92	BRS	55	(flexible with substrate and integrated adj (circuit circuits) and substrate with (bond bonding bonded)).clm.	US-PGPUB
93	BRS	14	(flexible with substrate and integrated adj (circuit circuits) and substrate with (bond bonding bonded) and die).clm.	US-PGPUB
94	BRS	12	(flexible adj substrate and integrated adj (circuit circuits) and substrate and (bond bonding bonded) and die).clm.	US-PGPUB

	Time Stamp	Comments	Error Definition	Errors	Ref #
88	2005/08/09 14:27				S92
89	2005/08/09 17:26				S93
90	2005/08/09 17:26				S94
91	2005/08/09 17:26				S95
92	2005/08/09 17:26				S96
93	2005/08/09 17:27				S97
94	2005/08/09 17:28				S98